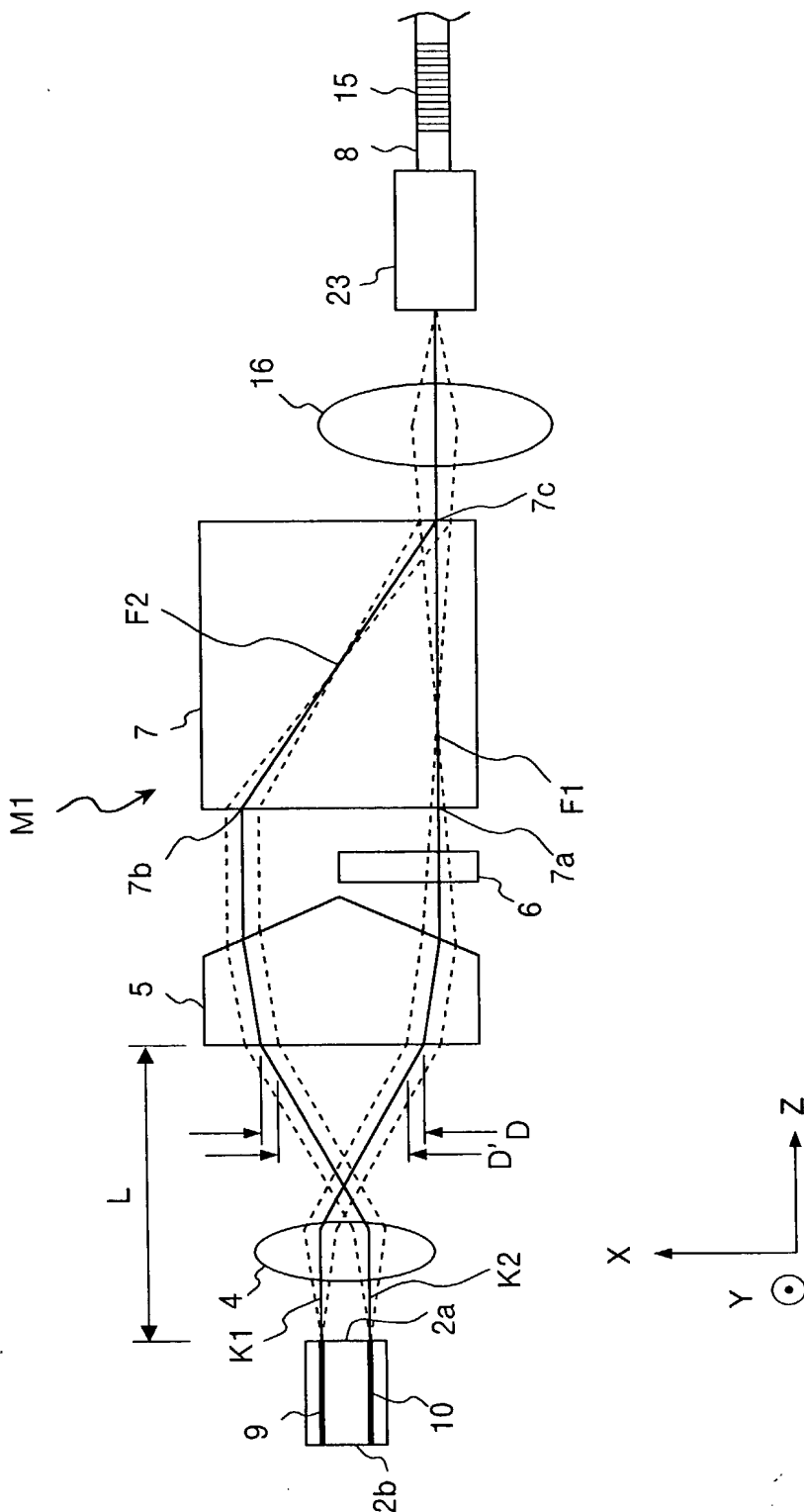


FIG. 2



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FIG.3A

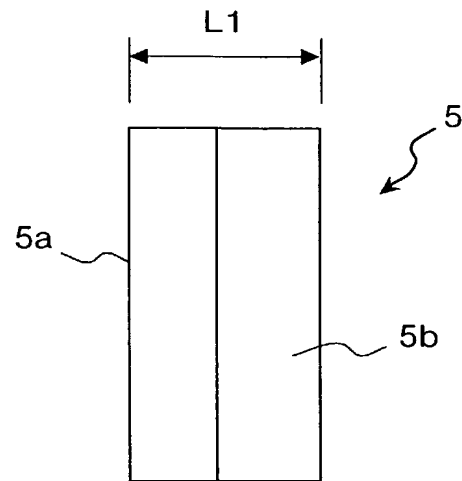
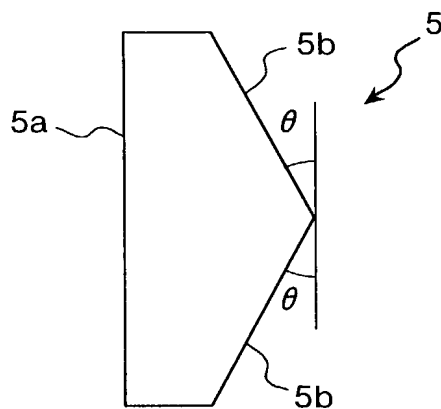


FIG.3B



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FIG.4A

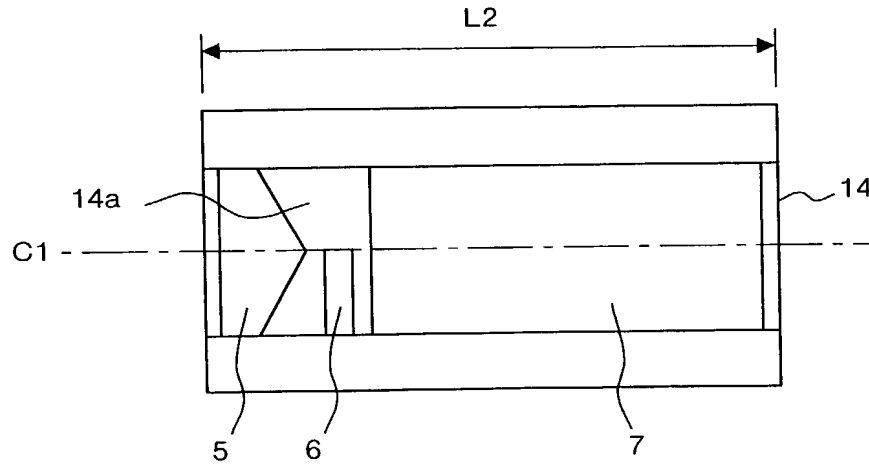


FIG.4B

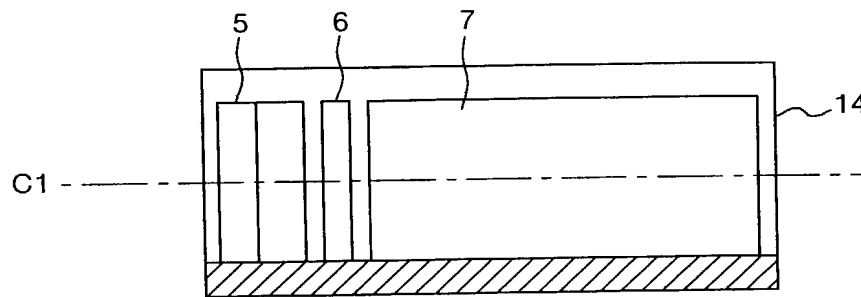
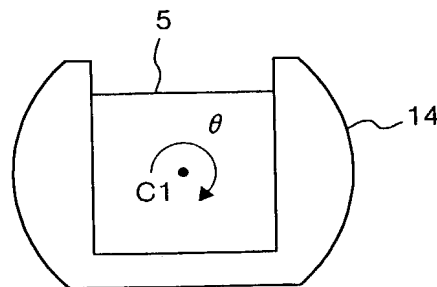


FIG.4C



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FIG.5A

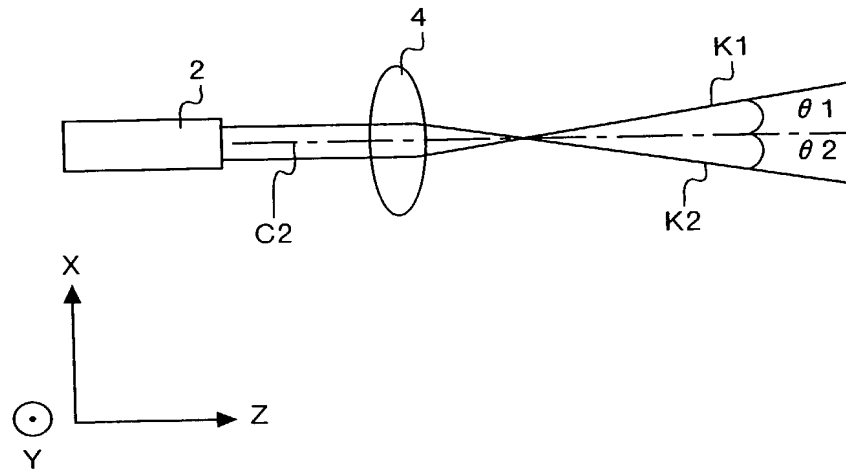
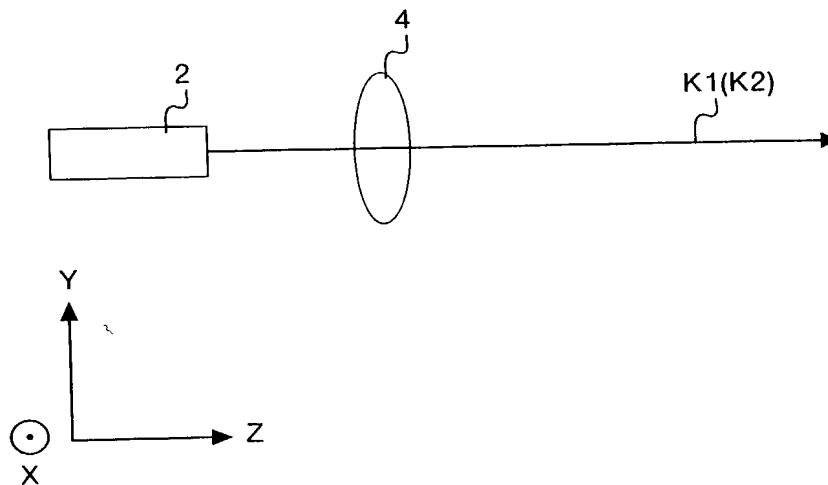


FIG.5B



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FIG.6A

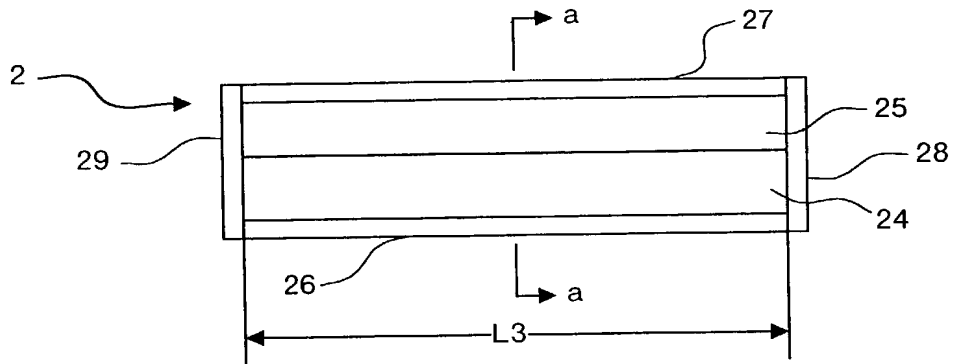
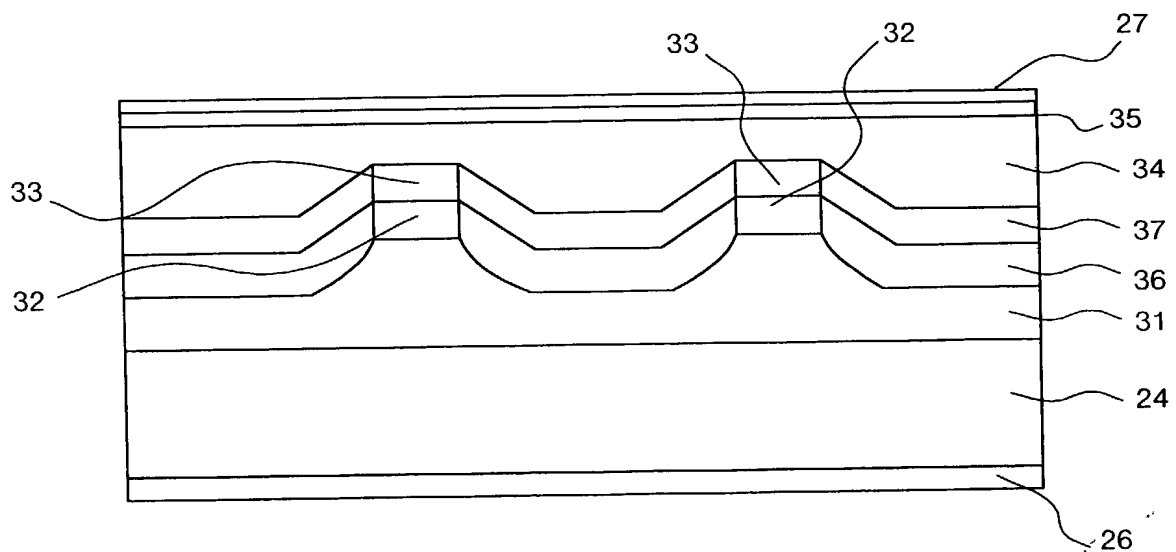
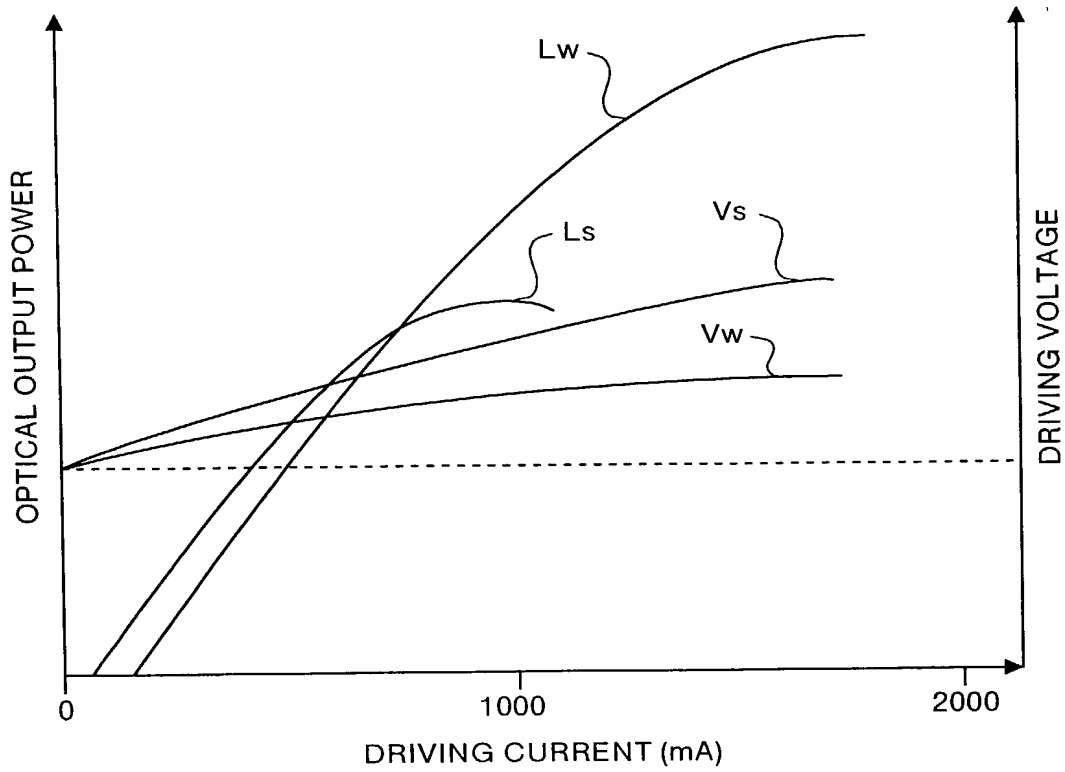


FIG.6B



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FIG.7



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FIG.8

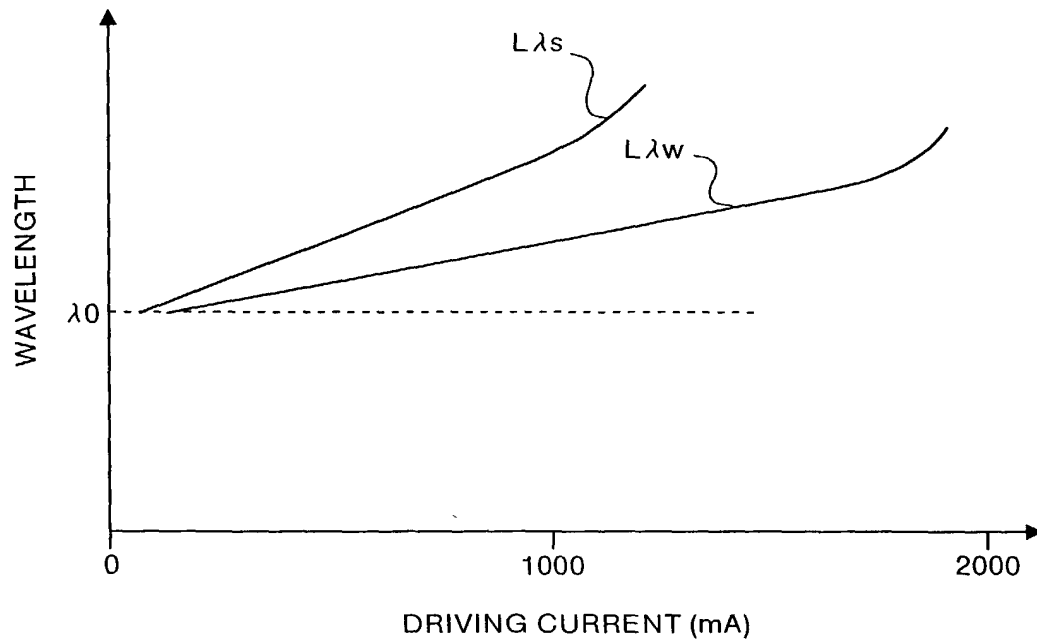


FIG.9

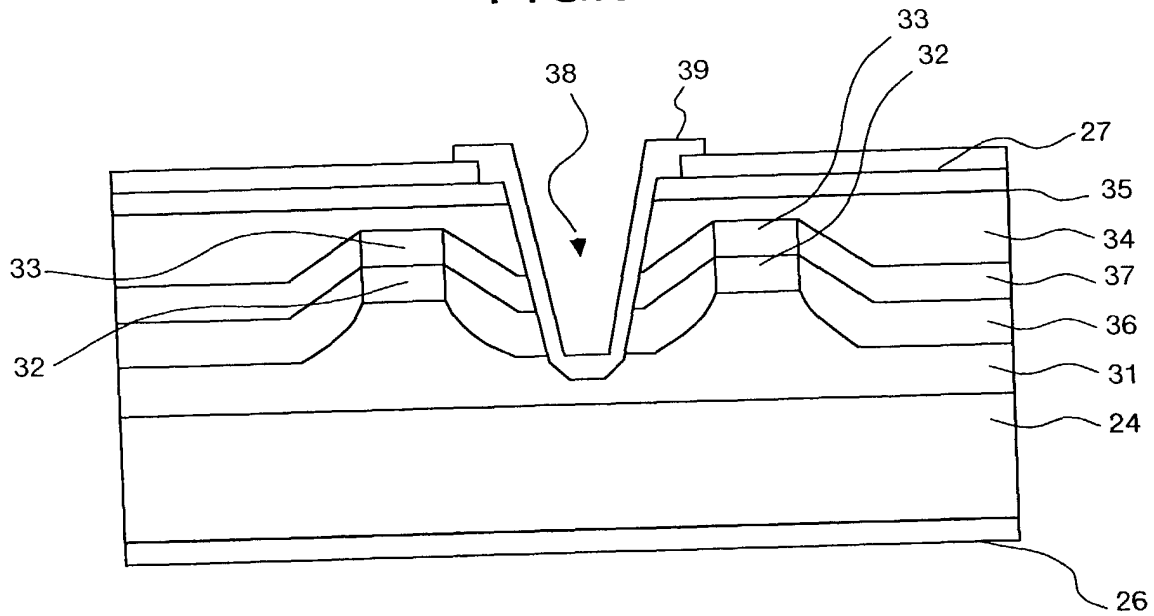
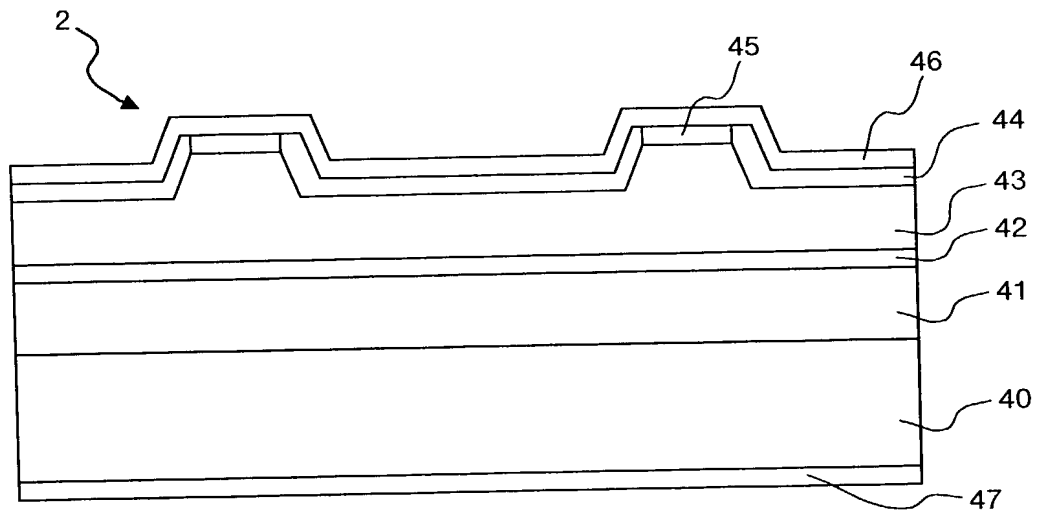


FIG.10



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FIG.11

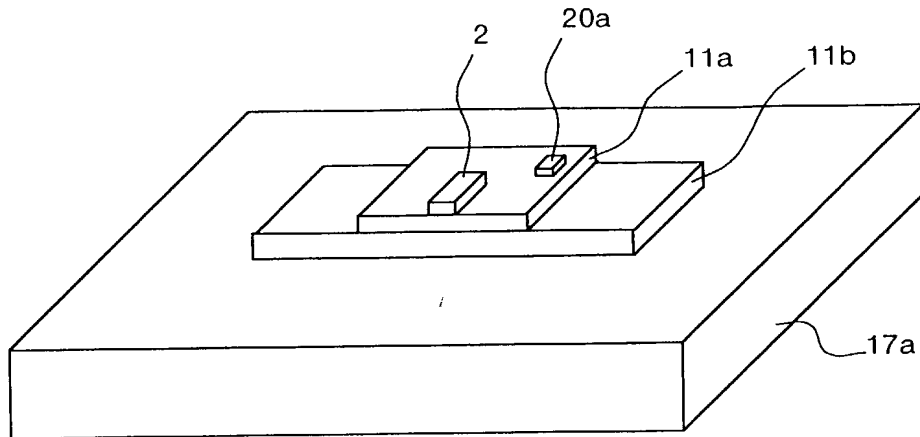


FIG.12

		A	B
UPPER HEAT SINK		CVD DIAMOND	AlN
LOWER HEAT SINK		AlN	AlN
HEAT OUTPUT [W]	LEFT ACTIVE LAYER	2.5	2.5
	RIGHT ACTIVE LAYER	2.5	2.5
TEMPERATURE [°C]	LEFT ACTIVE LAYER	37.96	49.53
	RIGHT ACTIVE LAYER	37.96	49.53
	UPPER MOUNT	26.76	26.77

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FIG.13

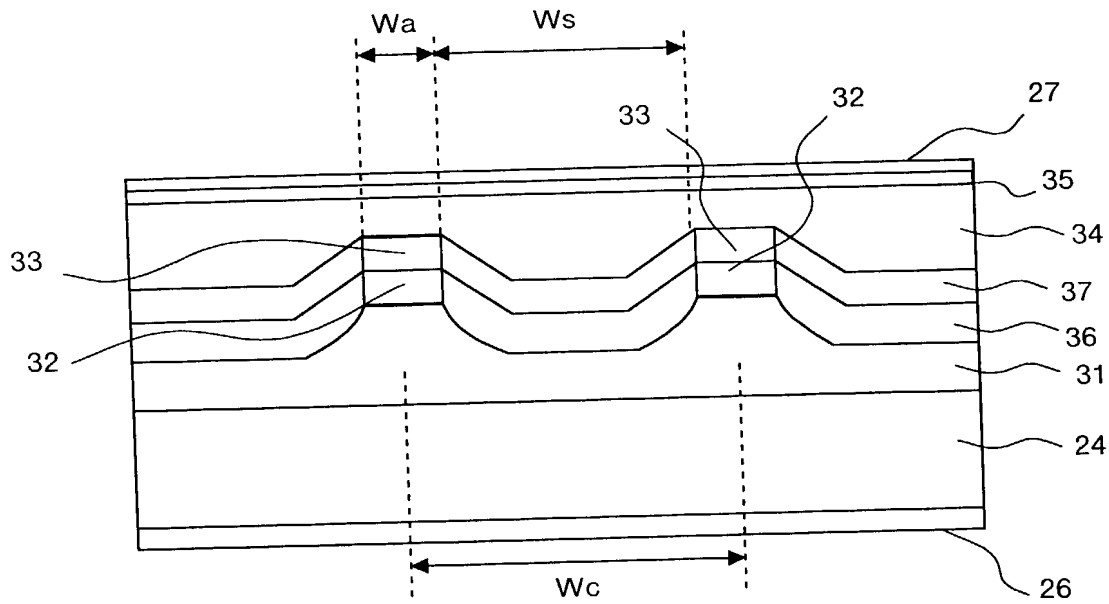
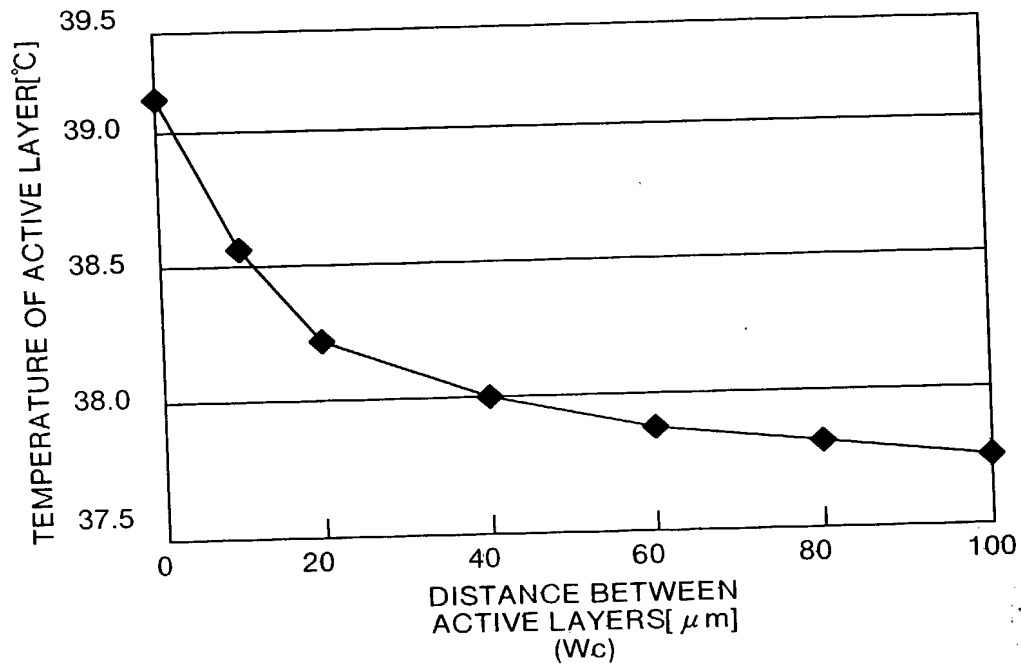
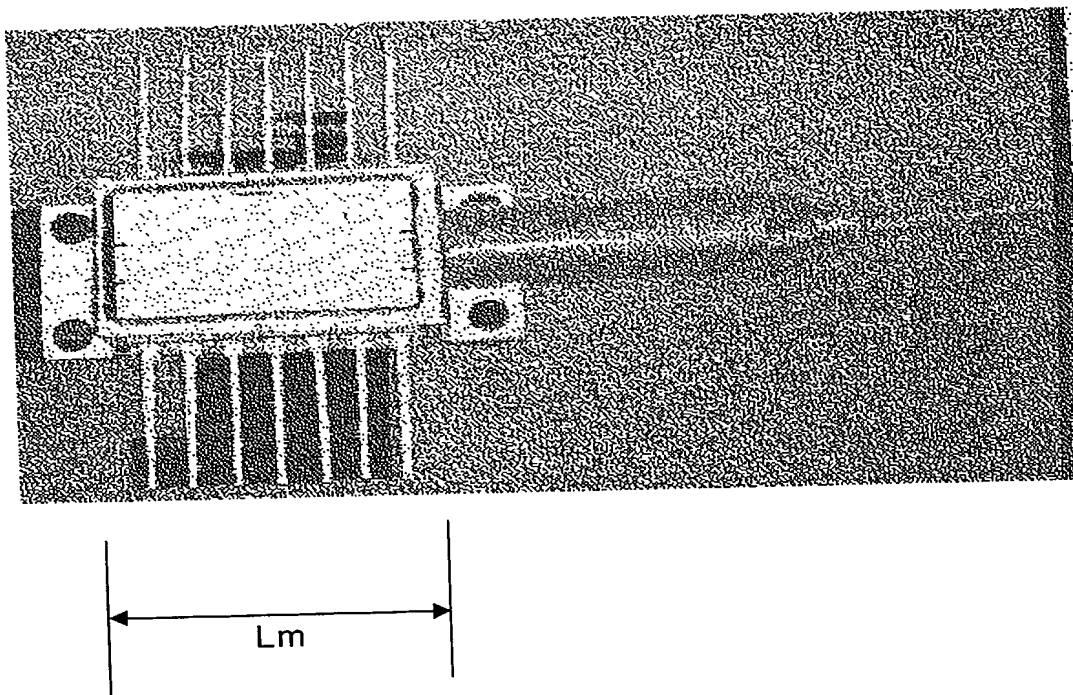


FIG.14



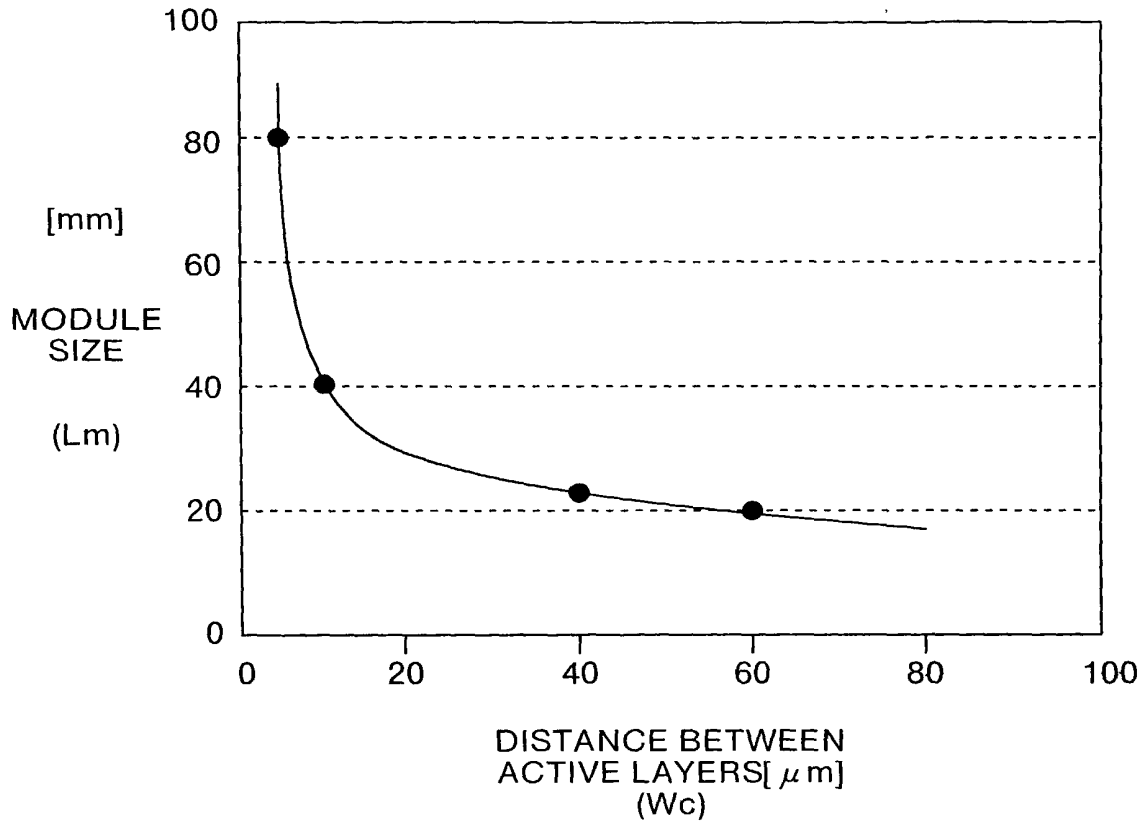
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FIG.15



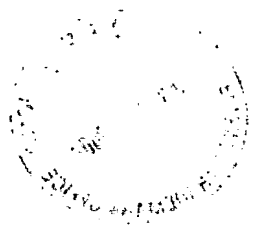
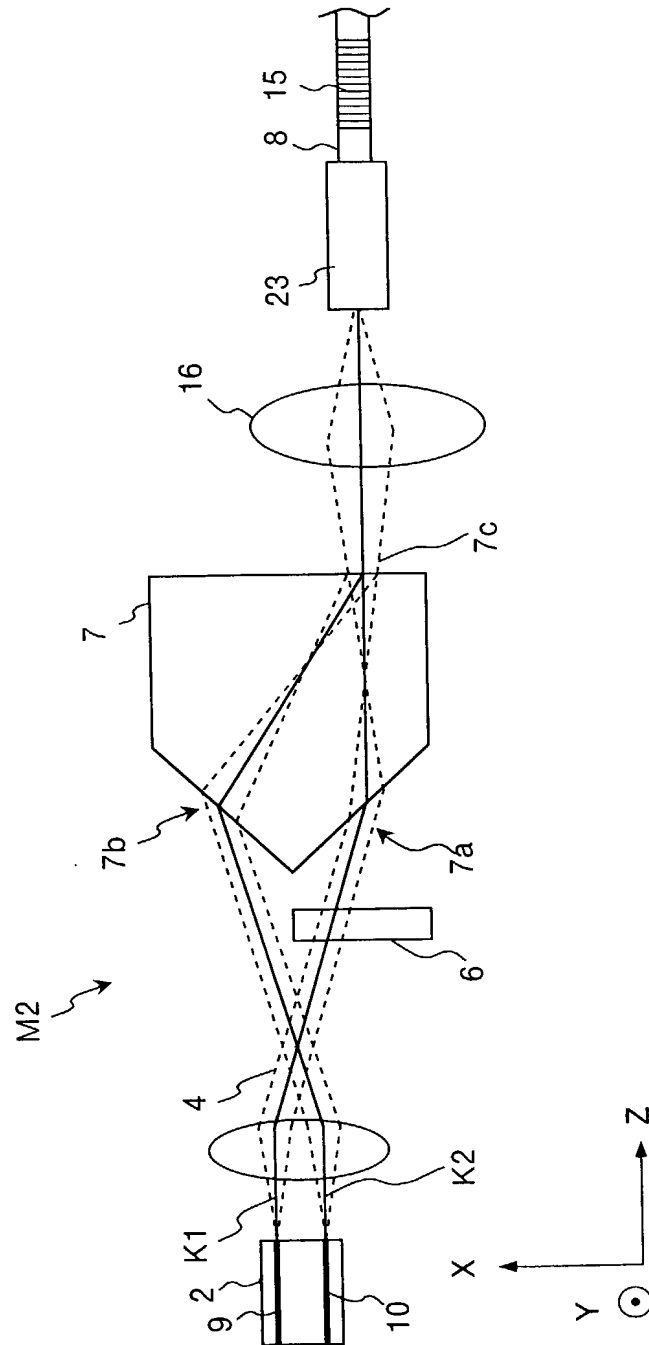
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2010-10-14
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FIG.16



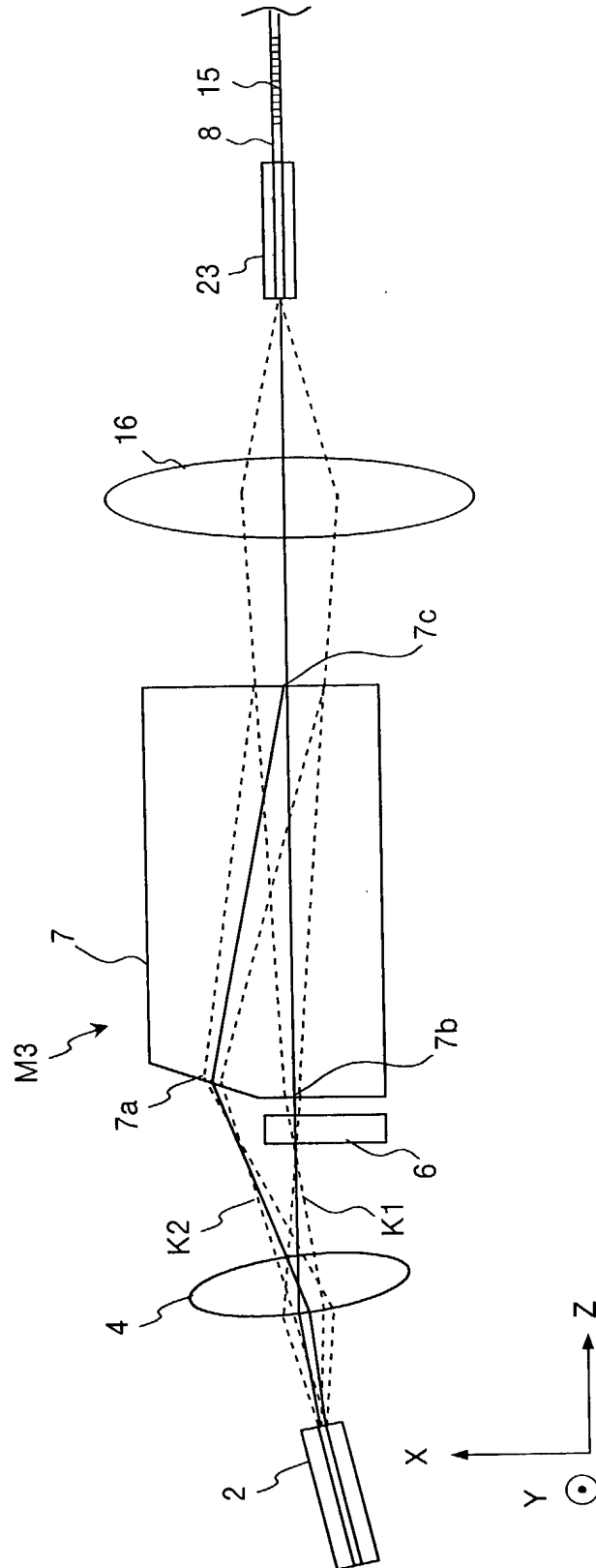
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FIG.17



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FIG.18



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FIG.19

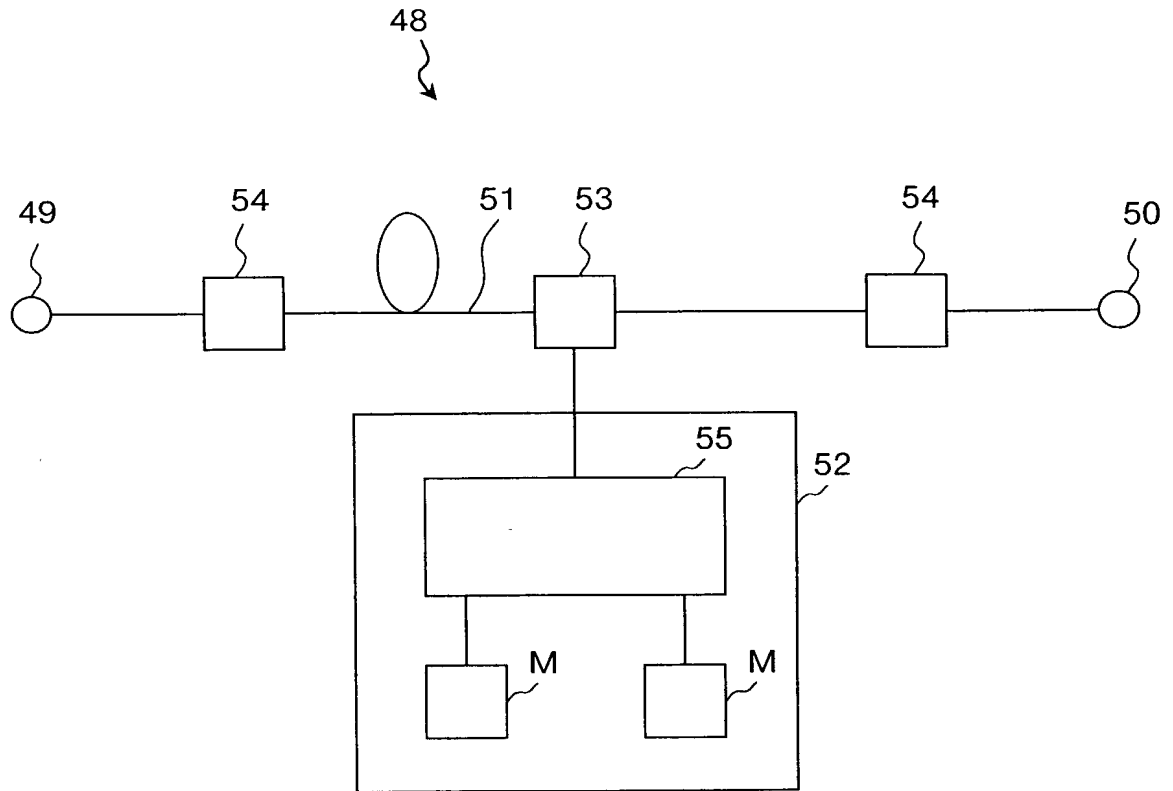


FIG.20

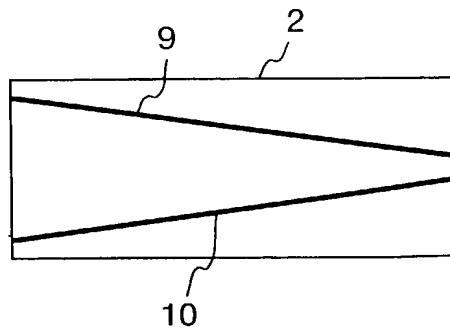


FIG.21

